



PROCESS/ PRODUCT CHANGE NOTIFICATION

This is to inform you that Micrel Inc. has qualified QSOP-16L and SOIC-14L/16L packages at Unisem Batam, Indonesia as an assembly site due to Micrel current subcontractors Unisem Ipoh, Malaysia notifying Micrel that they plan to exit the QSOP-16L and SOIC-14L/16L package manufacturing. If you have any questions concerning this change, please contact:

NAME: Hank Chou

EMAIL: hank.chou@micrel.com PHONE: +1-408-435-2422

TYPE OF CHANGE

We have qualified Unisem Batam as QSOP-16L and SOIC-14L/16L assembly source to replace the current Unisem Ipoh. The package type, material, form, fit and function will not be affected. These products will be shipped with the same packing and shipment format.

EFFECTIVITY

Starting Jan 1st, 2014, Micrel will begin to deliver the listed devices from Batam. After Jan 1st, 2014, the products shipped to customers could be either assembled from Ipoh or Batam. In order to make on-time deliveries to our growing end customers, we will reserve the flexibility to deliver certain part numbers at earlier date if un-expected material or capacity shortage occurs at Unisem Ipoh in the future.

PRODUCT ID (DESCRIPTION)

Please refer to the part numbers listed in the attached spread sheet "PPCN 130020 part list for QSOP-16L SOIC-14L 16L assembly at Batam" for Micrel's products that would be assembled at Batam site.

DESCRIPTION OF CHANGE

Micrel has qualified Unisem Batam, Indonesia for assembly of the listed Micrel products. This is due to Micrel current subcontractors Unisem Ipoh, Malaysia notifying Micrel that they plan to exit the QSOP-16L and SOIC-14L/16L package manufacturing.

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EFFECT OF CHANGE

There is no change in form, fit or function of the product. The land pattern, lead finish, lead layout, naming, and lead count are the same. There is no change in the die or testing. There is no change in moisture sensitivity rating.

QUALIFICATION

Batam is Micrel's qualified assembly subcontractor. Batam is already qualified and manufacturing PDIP, PLCC, SSOP, and SOICW packages in high volume production. Traceability is maintained by date code and lot number, and country of origin (CO) for all products. The parts made at Unisem Ipoh will have a "MY" country of origin mark, and the parts made at Batam will have an "IN" country of origin mark. We attach representative reliability reports for qualifying products assembled at Batam, Indonesia.

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RELIABILITY REPORT

DATE: 09/20/2013

QUALITY ENG:	PURPOSE:
H.GRIMM	NEW ASSEMBLY SITE FOR QSOP PACKAGE
	EME-G600 M/C MATTE TIN L/F 84-1LMRS4 D/A

PART NUMBER	PACKAGE TYPE ASSEMBLY LOCATION FAB LOCATION		FAB LOCATION	PROCESS NAME
MIC2010-1PZQS	QSOP_16L	UNISEM BATAM	Micrel, USA	BCD2
MICRF219 AYQS	QSOP_16L	UNISEM BATAM	AMS, Austria	CMOS 0.35

DIE QUALIFICATION RESULTS

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	168 HR Rej/ss	500 HR Rej/ss	1000 HR Rej/ss	
HTOL	JESD22, Method 108	1301	134054.01MQA	0/77	0/77	0/77	
High Temperature Operating Life Test	TA= + 125°C	1250	PC13561.1MQB	SKIP	0/77	0/77	
		1249	PC13561.1MQA	SKIP	0/77	0/77	

ELECTROSTATIC DISCHARGE

ELECTROSTATIC DISCHA	inge				
TEST DESCRIPTION	METHOD/CONDITIONS	DEVICE ID.	STRESS	RESULT Rej/ss	COMMENTS
ESD-HBM Human Body Model ATE Test @ Room +25C	R= 1500 Ohms C= 100 pF 1X +/- Voltage	MIC2010-1PZQS MICRF219AYQS	+/-500V +/-1000V +/-1500V +/-2000V +/-500V +/-1000V +/-1500V +/-2000V	0/3 0/3 0/3 0/3 0/3 0/3 0/3 0/3	
ESD-CDM Charged Device Model ATE Test @ Room +25C	JESD22-C101 1X +/- Voltage	MIC2010-1PZQS MICRF219AYQS	+/-500V +/-1000V +/-1500V +/-2000V +/-500V +/-1000V +/-1500V +/-2000V	0/3 0/3 0/3 0/3 0/3 0/3 0/3 0/3	

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TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss		COMMENTS
Tpeak + 260°C 3X Reflow						
With Level 1 Pre- conditioning	Ta= +85°C/85%RH	1249	PC13561.1MQA	0/77	0/77	
BIAS HUMIDITY	JESD22-A101	1250	PC13561.1MQB	0/45	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	500 HR Rej/ss	1000 HR Rej/ss	COMMENTS
Tpeak + 260°C 3X Reflow						
With Level 1 Pre- conditioning						
High Temperature Storage Life		1249	PC13561.1MQA	0/76	0/76	
High Town and Co.	Ta = +150°C	1250	PC13561.1MQB	0/76	0/76	
HTSL	JESD22-A103	1301	134054.01MQA	0/76	Rej/ss 0/76	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	1000 HR	2000 HR	COMMENTS
Tpeak + 260°C 3X Reflow		1249	PC13561.1MQA	0/77		
With Level 1 Pre- conditioning	Ta = -65°C/+150°C	1250	PC13561.1MQB	0/45		
TEMP CYCLE	JESD22-A104	1301	134054.01MQA	0/77		
				Rej/ss		COMMENTS
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	1000 cy		COMMENTS
Tpeak + 260°C 3X Reflow	15 PSIG	1249	PC13561.1MQA	0/45		
With Level 1 Pre- conditioning	Ta = +121°C/100%RH	1250	PC13561.1MQB	0/77		
PRESSURE POT	JESD22-A102	1301	134054.01MQA	0/77		
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss		COMMENTS
				O/V LU		
	TA = +25°C		MICRF219AYQS	I/O LU	0/6 0/6	
LATCH-UP	JESD-78		MIC2010-1PZQS	I/O LU O/V LU	0/6 0/6	

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HAST	JESD22-A110	1301	134054.01MQA	0/50			
With Level 1 Pre- conditioning	Ta= +131°C/85%RH						
Tpeak + 260°C 3X Reflow							
FLAMMABILITY	UL-94V-0 Certified	material flam	npounds used by Micrel mability certifications. use and we verify the c	Micrel require	s a Certificate	UL website or of Compliance	n-line list of from the
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	P/F		COMMENT	rs
CSAM INSPECTION	IPC/JEDEC JSTD-020	1301	134054.01MQA	PASS			
		1249	PC13561.1MQA	PASS			
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	P/F		COMMENT	rs .
PHYSICAL DIMENSIONS	MIL STD 883	1249	PC13561.1MQA	PASS	PT#4420848	.1	
		1250	PC13561.1MQB	PASS	PT#4424595	.1	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	P/F		COMMENT	rs .
RADIOGRAPHIC X-RAY	MIL STD 883 TM2010	1301	134054.01MQA	PASS			
		1249	PC13561.1MQA	PASS			
							T
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	MIN	MAX	AVE	РРК
WIRE PULL	MIL STD 883 TM2011	1250	PC13561.1MQB	7.7	9.7	8.6	3.08
	ASTM F-1269-89	1249	PC13561.1MQA	7.7	9.4	8.53	2.91
	MIC-100-1010						
BALL SHEAR	MIL STD 883 TM2011	1250	PC13561.1MQB	29.2	49.1	35.85	2.91
DALL SHEAR							
	ASTM F-1269-89	1249	PC13561.1MQA	32.3	39.6	36.31	2.04
	MIC-100-1010						

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DIE SHEAR	MIL STD 883 TM2011	1250	PC13561.1MQB	10.98	12.05	11.4	N/A
	ASTM F-1269-89	1249	PC13561.1MQA	9.8	12.62	11.8	N/A
	MIC-100-1010						
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	SAC	Sn +215	Sn +245	
TEST DESCRIPTION SOLDERABILITY	METHOD/CONDITIONS JESD22-B102		LOT ID. 134054.01MQA	SAC PASS	Sn +215 PASS	Sn + 245 PASS	

NOTES:

Passes Reliability Qualification and Released to Production.

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RELIABILITY REPORT

DATE: 09/25/2013

QUALITY ENG:	PURPOSE:
H.GRIMM	Unisem Batam SOIC 14-16L Package Qual

PART NUMBER	PACKAGE TYPE	ASSEMBLY LOCATION	FAB LOCATION	PROCESS NAME
MIC2537-2YM	SOIC-16L	UNISEM, BATAM	FORTUNE DR. SAN JOSE CA. USA	2537A-BCD2
MIC5157YM	SOIC-14L	M/C G600, D/A CRM1076NS,		5157B-BCDM
SY100EL34LZG	SOIC-16L	MATTE TIN LEAD FINISH		EL34-ASSET 1.2

DIE QUALIFICATION RESULTS

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	168 HR Rej/ss	1000 HR Rej/ss	COMMENTS
HTOL	JESD22, Method 108	1312	4A05377MQA	0/77	0/77	
High Temperature Operating Life Test	TA= + 125°C	1312	2A18063MQA	0/77	0/77	
	VCC =	1317	AA27231MEA	0/77	0/77	

PACKAGE QUALIFICATION RESULTS

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TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS
PRESSURE POT	JESD22-A102	1312	4A05377MQA	0/45	
With Level 2 Pre-	Ta = +121°C/100%RH	1312	2A18063MQA	0/45	
conditioning Tpeak + 260°C 3X Reflow	15 PSIG	1317	AA27231MEA	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS
HAST	JESD22-A110 (BIASED)	1312	4A05377MQA	0/45	Vin = 5.5 V
Will be 10 B	Ta= +131°C/85% RH	1312	2A18063MQA	0/45	No bias
With Level 2 Pre- conditioning	JESD22-A118 (UNBIASED)	1317	AA27231MEA	0/45	No bias
Tpeak + 260°C 3X Reflow					
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	1000 CY Rej/ss	COMMENTS

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TEMP CYCLE	JESD22-A104	1312	4A05377MQA	0/45			
With Level 2 Pre-	$Ta = -65^{\circ}C/+150^{\circ}C$	1312	2A18063MQA	0/45			
conditioning Tpeak + 260°C 3X Reflow		1317	AA27231MEA	0/45			
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	1000 HR Rej/ss		COMMENTS	
HTSL	JESD22-A103	1312	4A05377MQA	0/76			
High Temperature Storage	Ta = +150°C	1312	2A18063MQA	0/76			
Life With Level 2 Pre- conditioning Tpeak + 260°C 3X Reflow		1317	AA27231MEA	0/76			
FLAMMABILITY	UL-94V-0	All mold compo	unds used by Micrel mee rtifications. Micrel requir	et this standard. S	See the UL webs	ite on-line list o	of material
	Certified		ertifications on the web.	res a Certificate (or Compitance i	rom the asseme	ny nouse and
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	P/F	COMMENTS		
CSAM INSPECTION	IPC/JEDEC JSTD-020	1312	4A05377MQA	Pass			
		1312	2A18063MQA	Pass			
		1317	AA27231MEA	Pass			
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	P/F		COMMENTS	S
PHYSICAL DIMENSIONS	MIL STD 883	1312	4A05377MQA	Pass			
		1317	AA27231MEA	Pass			
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	P/F	COMMENT	S	
RADIOGRAPHIC X-RAY	MIL STD 883 TM2010	1312	4A05377MQA	Pass	5 samples		
		1312	2A18063MQA	Pass	5 samples		
		1317	AA27231MEA	pass	5 samples		
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	PKG	SAC +245C	Sn +245C	Sn +215C	
SOLDERABILITY	JESD22-B102	1312	14L SOIC	0/5	0/5	0/5	PASS
		1317	16L SOIC	0/5	0/5	0/5	PASS
NOTES: Passes Reliability Qualification	and Palacead to Production						
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